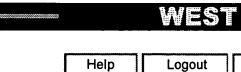
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1	L1	9696	204/192.\$ or 204/298.\$	USPAT; USOCR
2	L2	27	1 and (imp or (ion adj metal adj plasma))	USPAT; USOCR
3	L3	10	2 and wetting	USPAT; USOCR
4	L4	5213	204/192.\$ or 204/298.\$	USOCR; EPO; JPO; Derwent; IBM TDB
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6	L6	73274	c23c014/34\$ or sputter\$ or pvd or "physical vapor deposition" or "p.v.d."	USOCR; EPO; JPO; Derwent; IBM TDB
7	L7	8	6 and (imp or (ion adj metal adj plasma))	USOCR; EPO; JPO; Derwent; IBM TDB
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USPT,JPAB,EPAB,DWPI,TDBD	12 and wet\$4	30	<u>L3</u>
DWPI,USPT,EPAB,JPAB,TDBD	sputter\$4 and (IMP or (Ion\$4 adj metal adh plasma))	82	<u>L2</u>
DWPI,USPT,EPAB,JPAB,TDBD	sputter\$4 with (IMP or (Ion\$4 adj metal adh plasma))	40	<u>L1</u>

	Document ID	Issue Date	Current OR	Current XRef
1	US 6177350 B1	20010123	438/688	438/622 ; 438/629 ; 438/637 ; 438/643 ; 438/672 ; 438/675
2	US 6156645 A	20001205	438/648	438/656 ; 438/683 ; 438/685
3	US 6139699 A	20001031	204/192.15	204/192.12 ; 204/192.13 ; 204/192.22

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